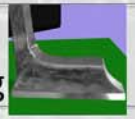
QuickSpec SMT Soldering Compliance Guide

IPC SMT Class Three Specifications

synopsis of select class 3 specifications please see current revision of IPC-A-610 for more details

Spec	DIM	Chip Component 	Gull Wing 	J Lead 	MELF 
Max Side Overhang	A	25% W or P *	25% W or 0.5mm	25% W ***	25% W or P *
End Overhang	B	Not permitted	***	***	Not permitted
Min End Joint Width	C	75%W or P	75% W	75% W	50% W or P *
Min Side Joint Length	D	Wetting	3 W or 75% L ****	150% W	75% R or 75% S*
Max Fillet Height	E	No contact to body	No contact to body	No contact to body	No Contact to Body
Min Fillet Height	F	G+25%H or **	G + T	G + T	G + 25% W or **
Solder Thickness	G	Wetting	Wetting	Wetting	Wetting
Min End Overlap	J	required			75% R

W= width of lead P= width of pad wetting = evidence of wetting must be visible H= height of lead R= depth of termination S = pad depth T= thickness of lead

* which ever is less and does not violate min electrical clearance

** G + 1 mm whichever is less

*** Does not violate minimum electrical clearance

**** see spec for more details

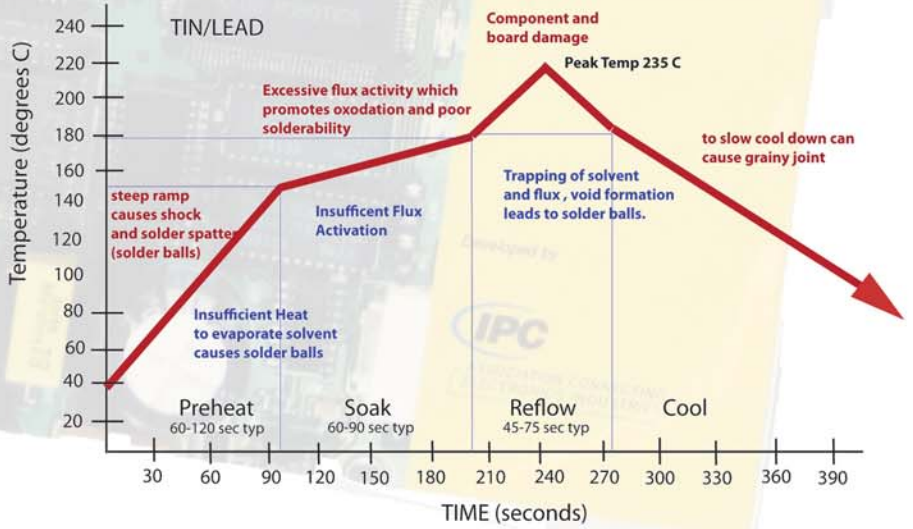
ESD Made Easy

ANSI/ESD S20.20 is the electronics industry`s benchmark for eliminating ESD related failures. It has three main principals and if you follow them you will eliminate the majority of your ESD related concerns.

1) **The operator, the work surface, and the ESDS device must always be at the same electrical potential. As a result, ESDS devices must only be handled at a properly grounded dissipative work surface and the operator must also be grounded. The work surface must be free of static producing insulators.**

2) **Any ESDS device must be stored or transported in a static shielding container, thus producing a "faraday cage".**

3) **If a necessary insulator is required in the ESD safe area, ionization must be used to eliminate the harmful static field.**



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